



Optimized drill design



新規開発ドリル加工事例

φ 0.4 Small-hole drilling performance

Work material: **R-1566** (halogen-free PCB material)
t1.6(6 layers 18/35/18 μ mCu) **3 panels / stack**

Entry sheet: Aluminum t0.15

N:100,000 min⁻¹ F:2.0 m/min f:20 μ m/rev

Set life:3,000 hits x 6 = Total 18,000hits

Work material : Panasonic Electric Works Co., Ltd.



φ 0.4

application: FBGA / BGA / HDI etc...

φ 0.4mm 加工事例

用途 半導体パッケージ、ビルドアップ用内層コア材 等



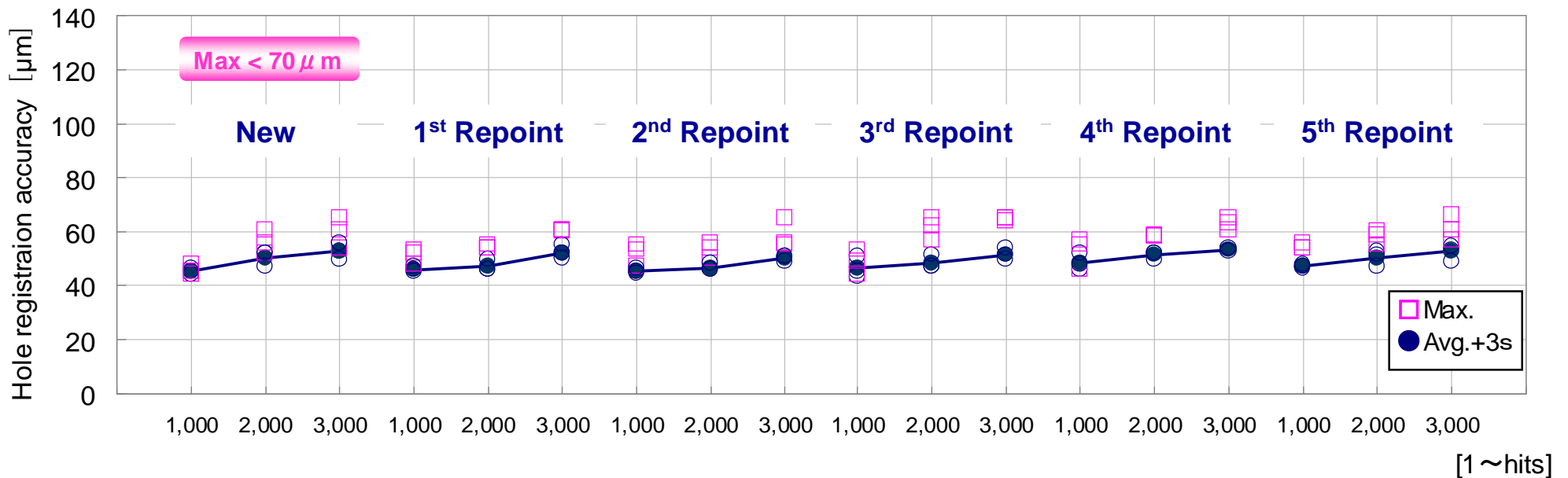
Drilling condition [加工条件]

Work material : **FR-4 R1566** t1.6 (6 layers 18/35/18 μ m Copper) **3 panels / stack**
 Entry sheet : Aluminum t0.15 Back-up board : SPB-CM
 N : 100,000 min⁻¹ F : 2.0 m/min f : 20 μ m/rev
 Set life:3,000 hits x 6 = Total 18,000hits

Halogen free material
 Promising hole quality!
 ハロゲンフリー基板における
 安定した品質の確保を実現

Performance of optimized drill design [新規開発ドリルの性能]

■ Hole registration accuracy [穴位置精度]





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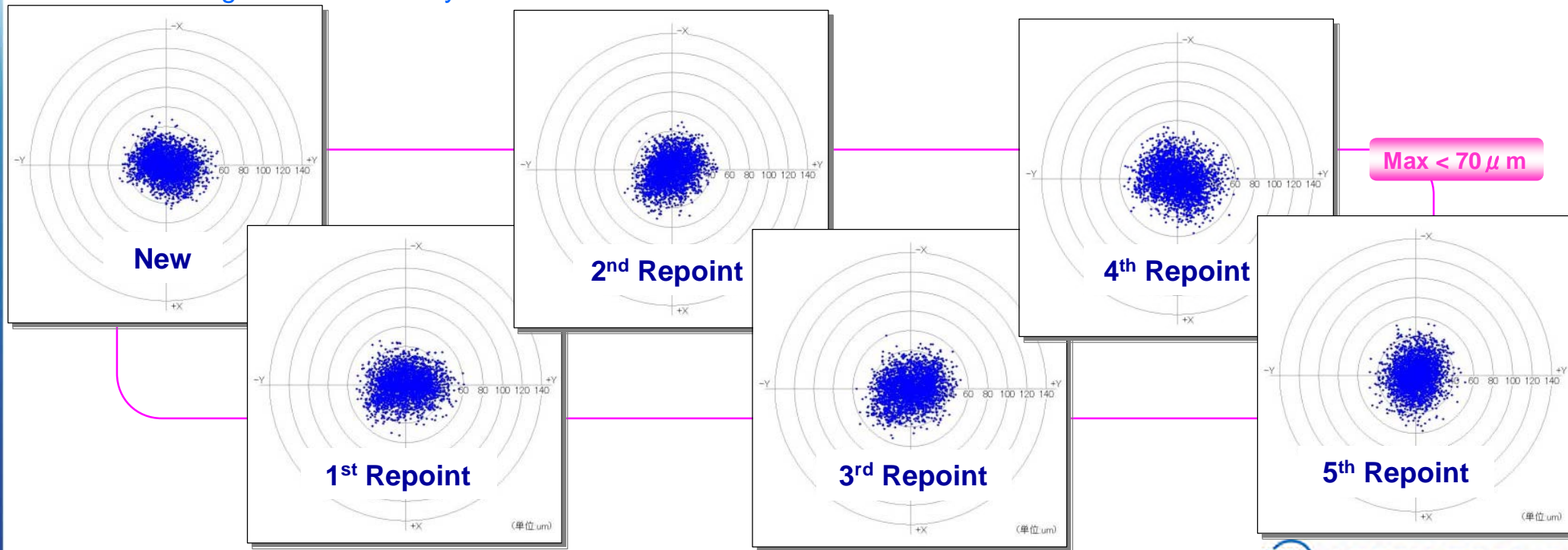
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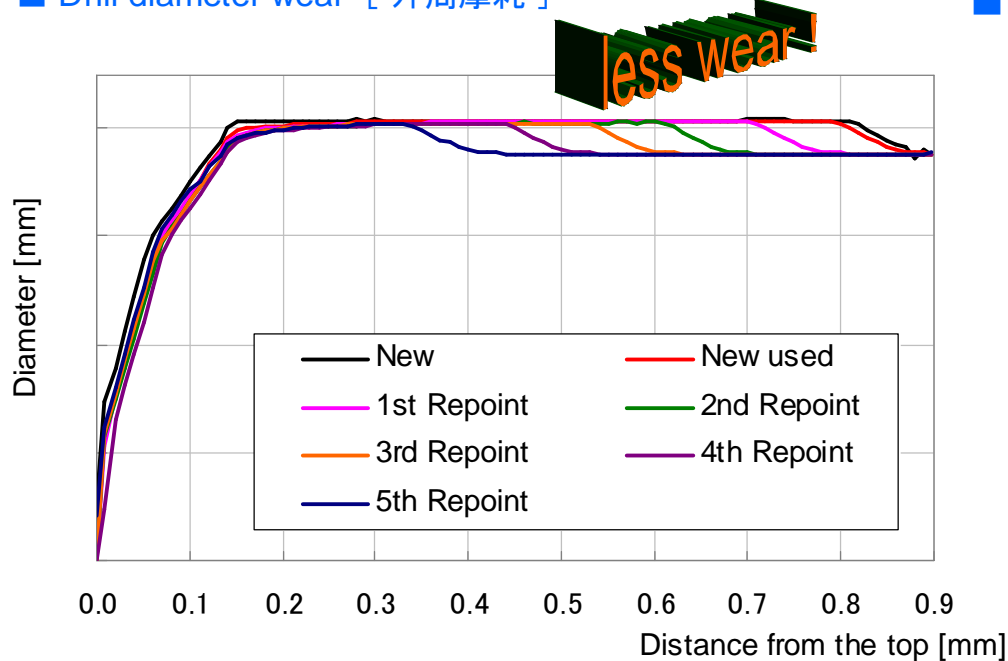
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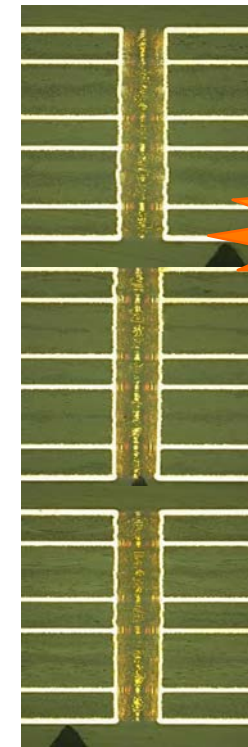
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Performance of optimized drill design [新規開発ドリルの性能]

■ Drill diameter wear [外周摩耗]



■ Hole wall roughness [内壁粗さ]



Top

Bottom

5th Repoint

Max < 15 μ m